

WHAT IS CLAIMED IS:

1. A method for producing a multi-layer foamed sheet having foam layers and non-foam layers by a multi-layer circular die coextrusion method, wherein the shear stress at the interface of each layer is 5000 Pa or higher and not higher than 50000 Pa.

2. The method for producing a multi-layer foamed sheet according to Claim 1, wherein the resin of said non-foam layer is a linear propylenic resin having a melt flow rate of 5 to 30 g/10 minutes.

3. The method for producing a multi-layer foamed sheet according to Claim 1, wherein the resin of said foam layer is a propylenic resin whose melt tension (MT) at 190°C and melt flow rate (MFR) at 230°C satisfy the following equation A:

$$MT \geq 7.52 \times MFR (-0.576)$$

$$[\text{Equation A}]$$

4. The method for producing a multi-layer foamed sheet according to Claim 1 wherein the resin of said foam layer is a propylene polymer (T) obtained by a polymerization method comprising a step for producing a crystalline propylene polymer moiety (A) having an intrinsic viscosity of 5 dl/g or higher and a step for producing a crystalline propylene polymer moiety (B) having an intrinsic viscosity less than 3 dl/g wherein the intrinsic viscosity of the entire resin is less than 3 dl/g and wherein the crystalline propylene polymer moiety (A) is present in an amount of 0.05 % by weight or higher and less than 35 % by weight based on the entire resin.

5. The method for producing a multi-layer foamed sheet according to Claim 1 wherein the layer structure is a two-material three-layered

structure of non-foam layer/foam layer/non-foam layer.

6. The method for producing a multi-layer foamed sheet according to any one of Claims 1 to 4 wherein the layer structure is a three-material five-layered structure of non-foam layer/recycle layer/foam layer/recycle layer/non-foam layer wherein said recycle layer is a non-foam recycle layer formed from a chip made by grinding any of the multi-layer foamed sheets according to any of Claims 1 to 4 or from a recycled pellet made by deaerating and pelletizing said chip.

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